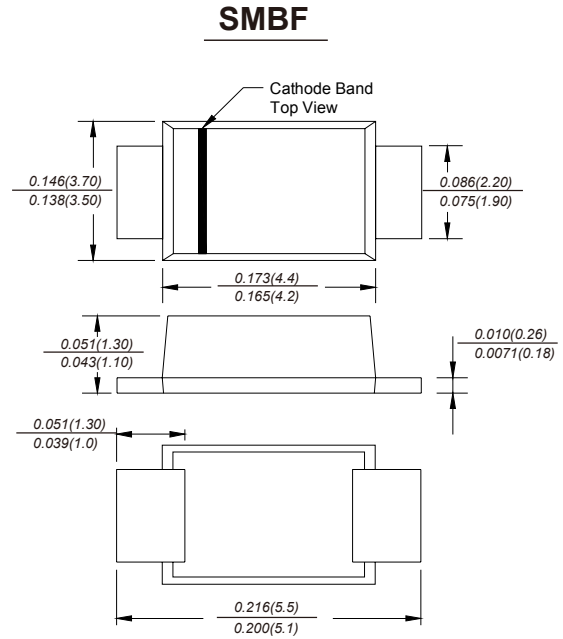


FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Ultra fast switching for high efficiency
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed
- 260°C/10 seconds at terminals
- Glass passivated chip junction

MECHANICAL DATA

- Case:** SMBF molded plastic body over passivated chip
- Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity:** Color band denotes cathode end
- Mounting Position:** Any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SL34BF	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	VOLTS
Maximum RMS voltage	V_{RMS}	28	VOLTS
Maximum DC blocking voltage	V_{DC}	40	VOLTS
Maximum average forward rectified current	$I_{(AV)}$	3.0	Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	80.0	Amps
Maximum instantaneous forward voltage at 3.0A	V_F	0.45	Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	0.3 5.0	mA
Typical junction capacitance (NOTE 1)	C_J	450	pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	50.0	°C/W
Operating junction temperature range	T_J	-50 to +150	°C
Storage temperature range	T_{STG}	-50 to +150	°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.5x0.5" (12.7x12.7mm) copper pad areas



Fig.1 Forward Current Derating Curve

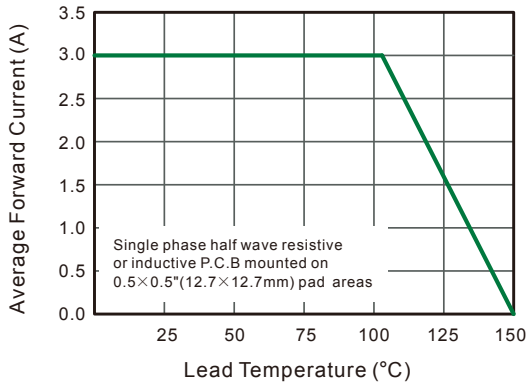


Fig.2 Typical Reverse Characteristics

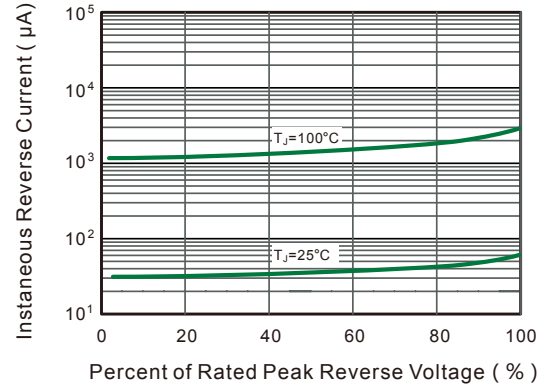


Fig.3 Typical Forward Characteristic

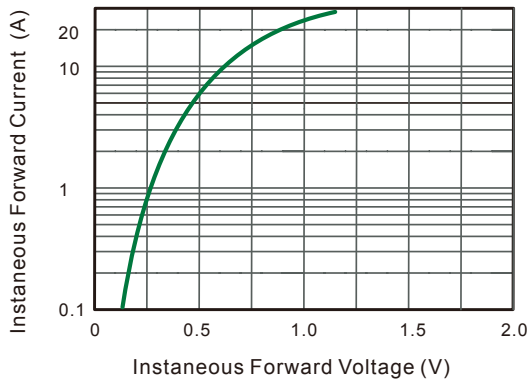


Fig.4 Typical Junction Capacitance

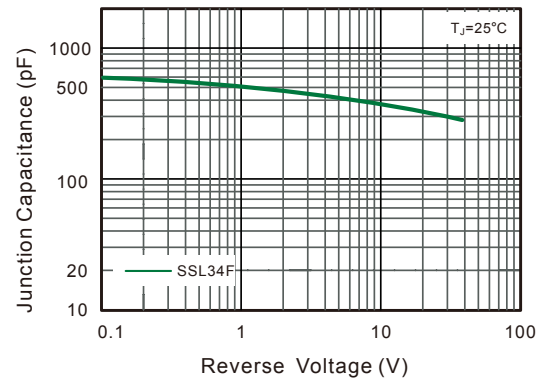


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

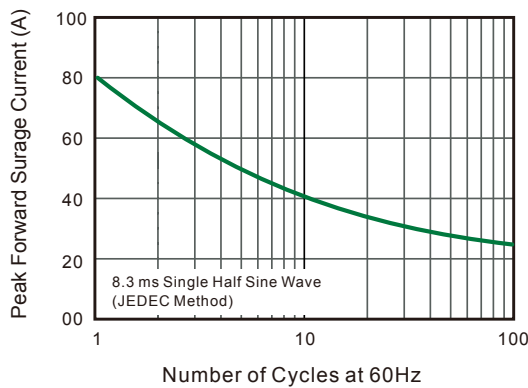


Fig.6- Typical Transient Thermal Impedance

